

ABSTRACT OF THE DISCLOSURE

The present invention relates to a polyamide resin composition comprising:

100 parts by weight of a polyamide resin mixture comprising

(A) 20 to 90% by weight of a polyamide 6 resin, a

polyamide 66 resin or mixture thereof and

(B) 10 to 80% by weight of an aromatic polyamide resin;

and

(C) 0 to 300 parts by weight of an inorganic filler,

said aromatic polyamide resin being having diamine units

comprising 10 to 50 mol% of paraxylylenediamine units and 50

to 90 mol% of methaxylylenediamine units, and aliphatic

dicarboxylic acid units.

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